



PATENT  
8013-1147

IN THE U.S. PATENT AND TRADEMARK OFFICE

In re application of

Hirokazu HONDA

Conf. 7187

Application No. 09/678,609

Group 2822

Filed October 4, 2000

Examiner D. Graybill

MULTILAYER INTERCONNECTION BOARD,  
SEMICONDUCTOR DEVICE HAVING THE  
SAME, AND METHOD OF FORMING THE  
SAME AS WELL AS METHOD OF MOUNTING  
THE SEMICONDUCTOR CHIP ON THE  
INTERCONNECTION BOARD

**AMENDMENT**

MS RCE  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

October 24, 2005

Sir:

In response to the Official Action of May 23, 2005,  
please amend the application as follows:

**Amendments to the Claims** are reflected in the listing  
of claims which begins on page 2 of this paper.

**Remarks** begin on page 7 of this paper.